

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/11/2022

Details for "TPS73512DRBR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS73512DRBR	NIPDAU	Level-2-260C-1 YEAR	TI MALAYSIA A/T	DRB 8	3x3x0.9	21.8

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Indium	7440-74-6	0.000001	0.001112	11	0.000005	0
Precious Metals	Gold	7440-57-5	0.089946	99.997776	999978	0.412334	4123
Precious Metals	Silver	7440-22-4	0.000001	0.001112	11	0.000005	0
Sub-Total			0.089948	100	1000000	0.412343	4123
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.00529	1.999947	19999	0.024251	243
Precious Metals	Silver	7440-22-4	0.18251	69.000064	690001	0.836669	8367
Thermoplastics	Epoxy	85954-11-6	0.076707	28.999989	290000	0.351643	3516
Sub-Total			0.264507	100	1000000	1.212563	12126
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	8.425333	99.249994	992500	38.623727	386237
Other Nonferrous Metals and Alloys	Chromium	7440-47-3	0.022071	0.259995	2600	0.101179	1012
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.021223	0.250006	2500	0.097291	973
Zinc and Its Alloys	Zinc	7440-66-6	0.020374	0.240005	2400	0.093399	934
Sub-Total			8.489001	100	1000000	38.915596	389156
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.145534	95.120261	951203	0.667162	6672
Precious Metals	Gold	7440-57-5	0.001193	0.779739	7797	0.005469	55
Precious Metals	Palladium	7440-05-3	0.006273	4.1	41000	0.028757	288
Sub-Total			0.153	100	1000000	0.701388	7014
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	10.816312	90.5	905000	49.584542	495845
Other Plastics and Rubber	Carbon Black	1333-86-4	0.059759	0.500003	5000	0.273949	2739
Thermoplastics	Epoxy	85954-11-6	1.075655	8.999997	90000	4.931058	49311
Sub-Total			11.951726	100	1000000	54.789549	547895
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.865697	100	1000000	3.968561	39686
Sub-Total			0.865697	100	1000000	3.968561	39686
Total			21.813879			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.